



ORV3 20U2N Server

Key Features

- OCP ORV3 Compliance
- 20U Rack-Mountable
- Support Busbar Power Solution
- Support OCP DC-MHS M-SDNO Class A/B HPM
- Support OCP 3.0 NIC Network Interface
- Support E1.S & E3.S SSD
- Modular Front I/O Modules
- Support Air/DLC Thermal Solution

Applications



HPC



AI



Deep Learning

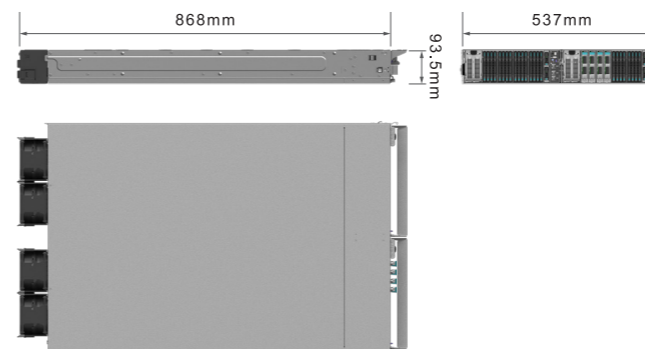


Data Analytics

Specification

Application	Suit in ORV3 open rack server, be applied to computing node & GPU node
MB Board	Single or dual sockets per node Support OCP DC-MHS M-SDNO Class A/B board size
Storage	2x EDSFF E1.S SSD per node 4~16x EDSFF E3.S 1T SSD per node 2~4x EDSFF E3.S 2T SSD per node
Network	2~4x OCP NIC 3.0 (SFF/TSFF) slots per node
Expansion Slots	2x LP PCIE Gen5 x16 slot per node 1x LP + 1x FHHL PCIE Gen5 x16 slots by optional module
System Fan	2~4x 92x56mm Fans or 92x38mm Fans with anti circle air-flow flaps
Thermal Solution	Air cooling or optional DLC (Direct Liquid Cooling) module with blind-mate quick connector for node installation
Dimensions(W x D x H)	537 x 868 x 93.5 mm
Form Factor	OCP 20U rackmount
Operation Temp.	-5°C – 45°C
Storage Temp.	-40°C – 70°C
Humidity	10% – 90% relative (non-condensing)

Dimension Details



For more product information and sales inquiries :

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Specifications are subject to change without notice.